

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT4363388

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
LEI WANG	04/18/2016
HONGYUAN ZHANG	04/18/2016
YAKUN SUN	04/18/2016
LIWEN CHU	04/19/2016
JINJING JIANG	04/19/2016
YAN ZHANG	04/18/2016
HUI-LING LOU	04/18/2016
RECEIVING PARTY DATA	
Name:	MARVELL SEMICONDUCTOR, INC.
Street Address:	5488 MARVELL LANE
City:	SANTA CLARA
State/Country:	CALIFORNIA
Postal Code:	95054
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	15135428
CORRESPONDENCE DATA	
Fax Number:	(408)222-2755
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	4082222500
Email:	syzemore@marvell.com
Correspondent Name:	KELVIN VIVIAN
Address Line 1:	5488 MARVELL LANE
Address Line 4:	SANTA CLARA, CALIFORNIA 95054
ATTORNEY DOCKET NUMBER:	MP6349
NAME OF SUBMITTER:	KELVIN VIVIAN
SIGNATURE:	/KELVIN VIVIAN/
DATE SIGNED:	04/11/2017

Total Attachments: 2

source=MP6349 EXECUTED Assign INV-MSI#page1.tif

source=MP6349 EXECUTED Assign INV-MSI#page2.tif

ASSIGNMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, we, the undersigned,

**Lei Wang, Hongyuan Zhang, Yakun Sun, Liwen Chu,
Jinjing Jiang, Yan Zhang, and Hui-Ling Lou**

who have created a certain invention for which an application for United States Letters Patent was executed by me concurrently herewith and entitled:

Channel Bonding Operations in Wireless Communications

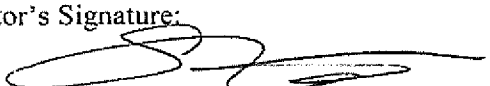
Do hereby sell, assign and transfer to Marvell Semiconductor, Inc., a corporation of California, having a place of business at 5488 Marvell Lane, Santa Clara, CA 95054, its successors, assigns, and legal representatives, the full and exclusive right to said invention and said application and to any and all inventions described in said application for the United States, its territorial possessions and all foreign countries, and the entire right, title and interest in and to any and all Letters Patent which may be granted therefor in the United States, its territorial possessions and all foreign countries; and in and to any and all continuations-in-part, continuations, divisions, substitutes, reissues, extensions thereof, and all other applications for Letters Patent relating thereto which have been or shall be filed in the United States, its territorial possessions and/or any foreign countries, and all rights, together with all priority rights, under any of the international conventions, unions, agreements, acts, and treaties, including all future conventions, unions, agreements, acts, and treaties;

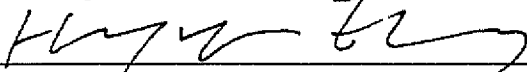
Do hereby further sell, assign and transfer to Marvell Semiconductor, Inc., its successors, assigns, and legal representatives, the full and exclusive right to United States Provisional Patent Application Nos. 62/151,938, filed April 23, 2015, entitled, Channel Bonding Operations in WirelessLAN, and 62/297,242, filed February 19, 2016, entitled, Channel Bonding Operations in WirelessLAN, and to any and all inventions described in said provisional patent application(s) for the United States, its territorial possessions and all foreign countries, and the entire right, title and interest in and to any and all Letters Patent which may be entitled to the benefit thereof in the United States, its territorial possessions and all foreign countries; and in and to any and all continuations-in-part, continuations, divisions, substitutes, reissues, extensions thereof, and all other applications for Letters Patent relating thereto which have been or shall be filed in the United States, its territorial possessions and/or any foreign countries, and all rights, together with all priority rights, under any of the international conventions, unions, agreements, acts, and treaties, including all future conventions, unions, agreements, acts, and treaties;

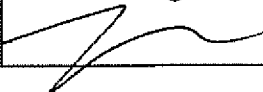
Agree that Marvell Semiconductor, Inc., hereinafter referred to as Assignee, may apply for and receive Letters Patent for said invention and said inventions, hereinafter referred to as said invention, in its own name, in the United States, its territorial possessions, and all foreign countries; and that, when requested to carry out in good faith the intent and purpose of this assignment, at the expense of said Assignee, its successors, assigns and legal representatives, the undersigned will execute all continuations-in-part, continuations, divisions, substitutes, reissues, extensions thereof, execute all rightful oaths, assignments, powers of attorney and other papers, testify in any legal or quasi legal proceedings; communicate to said Assignee, its successors, assigns or legal representatives all facts known to the undersigned relating to said invention and the history thereof; and generally do everything possible which said Assignee, its successors, assigns, or legal representatives shall consider desirable for aiding in securing, maintaining and enforcing proper patent protection for said invention and for vesting title to said invention and all applications for patents on said invention in said Assignee, its successors, assigns, or legal representatives; and

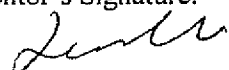
Covenant with said Assignee, its successors, assigns, or legal representatives that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

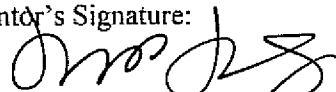
IN TESTIMONY WHEREOF I have hereunto set MY signature on the date indicated below.

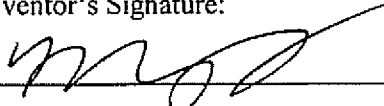
Full Name of First Inventor:	
Lei Wang	
Inventor's Signature:	Date: Month/Day/Year
	4/18/16

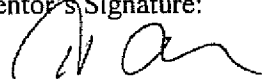
Full Name of Second Inventor:	
Hongyuan Zhang	
Inventor's Signature: 	Date: Month/Day/Year 4/18/2016

Full Name of Third Inventor:	
Yakun Sun	
Inventor's Signature: 	Date: Month/Day/Year 4/18/2016

Full Name of Fourth Inventor:	
Liwen Chu	
Inventor's Signature: 	Date: Month/Day/Year 04/19/2016

Full Name of Fifth Inventor:	
Jinjing Jiang	
Inventor's Signature: 	Date: Month/Day/Year 04/17/2016

Full Name of Sixth Inventor:	
Yan Zhang	
Inventor's Signature: 	Date: Month/Day/Year 04/18/2016

Full Name of Seventh Inventor:	
Hui-Ling Lou	
Inventor's Signature: 	Date: Month/Day/Year 4/18/2016